

Excellent Integrated System Limited

Stocking Distributor

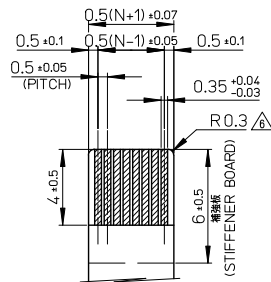
Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Molex Connector Corporation](#)
[0527450497](#)

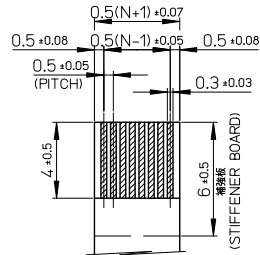
For any questions, you can email us directly:

sales@integrated-circuit.com

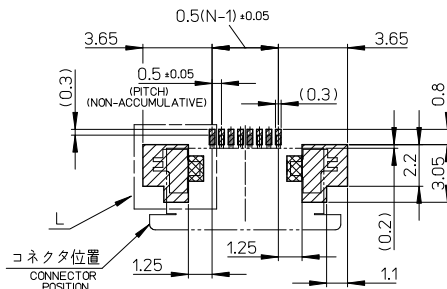
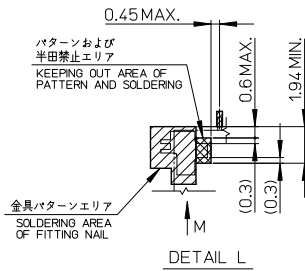
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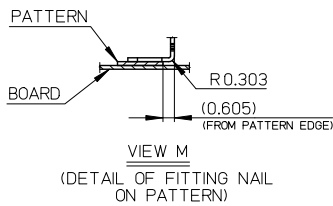
適合金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3±0.03/-0.03



適合金めっきFFC推奨寸法
APPLICABLE FFC OF GOLD
PLATING RECOMMENDED DIMENSION
仕上がり厚さ: 0.3±0.03
THICKNESS: 0.3±0.03/-0.03



参考基板レイアウト
(マウント面)
RECOMMENDED P.C. BOARD
PATTERN DIMENSION (REF.)
(MOUNTING SIDE)



注記NOTES

1. 使用材料

MATERIAL

ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
アクチュエータ: ポリフェニレンスルフィド (PPS)、ガラス充填、UL94V-0、黒
ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
ターミナル: リン青銅、ニッケル下地金めっき (t=0.2)
TERMINAL: PHOSPHOR BRONZE, GOLD OVER NICKEL PLATING
金具: リン青銅、ニッケル下地金めっき (t=0.2)
FITTING NAIL: PHOSPHOR BRONZE, TIN OVER NICKEL PLATING

2. エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART

NO.52745-**-59 SHOULD BE LOCKED.

3. ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、

基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。

MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM

DATUM-H.

UPPER DIRECTION: 0.1 MAXIMUM

LOWER DIRECTION: 0.15 MAXIMUM

4. 偶数極に適用

APPLY FOR EVEN CIRCUIT.

5. ハ・ターン制動止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

6. R0.3は、FPCの胴体部にかからないこと

R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

7. ELV 及び RoHS 適合品

ELV AND RoHS COMPLIANT

FPCについて:

打抜き方向は導体側から補強板を推奨致します。

補強フィルム材質はポリアミドを推奨致します。

接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

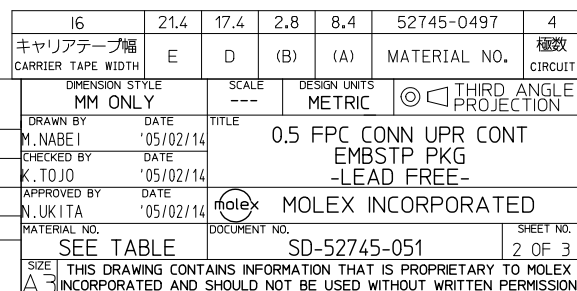
RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.

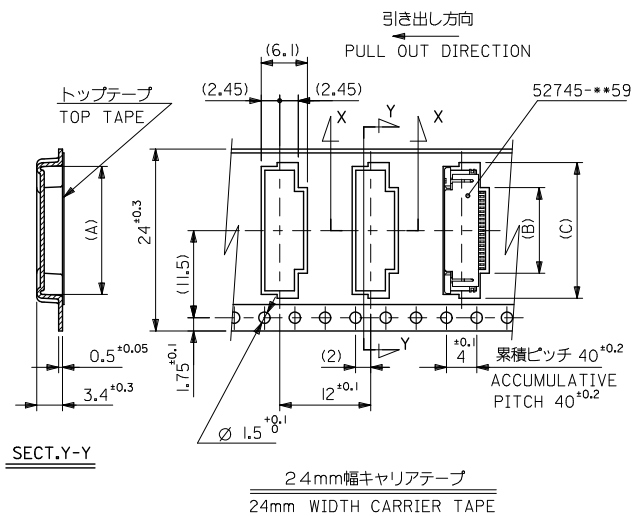
RECOMMENDED MATERIAL: STIFFENER FILM: POLYIMIDE

BONDING AGENT: THERMOSETTING BONDING AGENT

THIRD ANGLE PROJECTION	
SCALE 5:1	DESIGN UNITS METRIC

GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
10 UNDER	± ---	DRAWN BY M. NABEI	DATE '05/02/14	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) GOLD PLATING		
10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '05/02/14			
30 OVER	± ---	APPROVED BY N. UKITA	DATE '05/02/14			
ANGULAR ± --- °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-52745-050		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		





17.4	10.8	16.4	52745-2097	20
16.9	10.3	15.9	-1997	19
16.4	9.8	15.4	-1897	18
15.9	9.3	14.9	-1797	17
15.4	8.8	14.4	-1697	16
14.9	8.3	13.9	-1597	15
14.4	7.8	13.4	-1497	14
13.9	7.3	12.9	-1397	13
13.4	6.8	12.4	-1297	12
12.9	6.3	11.9	-1197	11
12.4	5.8	11.4	-1097	10
11.9	5.3	10.9	-0997	9
11.4	4.8	10.4	-0897	8
10.9	4.3	9.9	-0797	7
10.4	3.8	9.4	52745-0697	6

キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	MATERIAL NO.	極数 CIRCUIT
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REVISED EC NO. J2009-2061 DRAWN: KON CHKD: MATSUMOTO APPR: UKITA 2009/05/20 2009/05/21 2009/05/21	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	TITLE 0.5 FPC CONN UPR CONT EMBSTP PKG -LEAD FREE- MOLEX INCORPORATED SD-52745-051	SHEET NO. 3 OF 3
		10 UNDER	± ---	DRAWN BY M. NABEI	DATE '05/02/14					
		10 OVER 30 UNDER	± ---	CHECKED BY K. TOJO	DATE '05/02/14					
		30 OVER	± ---	APPROVED BY N. UKITA	DATE '05/02/14					
		ANGULAR ± --- °		MATERIAL NO.			DOCUMENT NO.			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE						
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						